NPC

OVERVIEW

The 5060Hxx series are LV-PECL output oscillator ICs with 125°C operating temperature that support a wide output frequency range ideal for high-frequency applications typical in high-speed communications devices. They employ an oscillator circuit optimized for compact, 3rd overtone crystal elements, making them ideal for use as compact, crystal oscillator modules. The oscillator circuit uses voltage regulator drive to achieve a low drive level.

FEATURES

- Operating supply voltage range: 2.25 to 3.63V
- Recommended oscillation frequency range (varies with version) 25MHz to 250MHz fundamental oscillation 50MHz to 220MHz 3rd overtone oscillation
- -40 to 125°C operating temperature range
- LV-PECL output
- Oscillation detection circuit built-in

- Frequency divider built-in
- Selectable by version: f_0 , $f_0/2$
- Standby function
- High impedance in standby mode, oscillator stops
- Power-saving pull-up resistor built-in (OE pin)
- Wafer form (WF5060Hxx)
- Chip form (CF5060Hxx)

SERIES CONFIGURATION

Oscillation	Recommended	C ₀ cancellation	Recommend	Output frequency (pF)					
mode	oscillation frequency range f ₀ *1[MHz]	circuit	C ₀ value ^{*2} [pF]	f ₀	f ₀ /2				
	25 to 100		to 1.5 ^{*3}	-	5060HL7 ^{*5}				
fundamental	100 to 175	No	$(\text{to } 2.0)^{*4}$	5060HM6 ^{*5}	-				
	175 to 250	Yes	1.2 to 1.8	5060HF6 ^{*6}					
	175 to 220	ies		3000110	-				
	50 to 63	Na	No	No	No	Ne	to 2.0 ^{*3}	5060HA6	-
3rd overtone	62 to 80	INO	$(\text{to } 2.5)^{*4}$	5060HB6	-				
fundamental	80 to 107		1.0. 0.0*3	5060HC6	-				
	100 to 140	Yes	$1.0 \text{ to } 2.0^{*3}$ (0.8 to 2.5) ^{*4}	5060HD6	-				
	140 to 175		(0.0 @ 2.5)	5060HE6	-				

^{*1.} The oscillation frequency is a yardstick value derived from the crystal used for NPC characteristics authentication. However, the oscillation frequency range is not guaranteed. Specifically, the characteristics can vary greatly due to crystal characteristics and mounting conditions, so the oscillation characteristics of components must be carefully evaluated.

*3. Normal recommended range based on the oscillator circuit design.

*4. Values in () are full range values. If using these ranges, careful evaluation is recommended before implementation.

*5. L and M versions are recommended for use with crystals such as compact AT cut crystals with extremely low C_0 and R_1 , and inverted mesa crystals. *6. The F version is adjusting C_0 cancellation circuit rather hard to have a negative resistance by a high frequency.

A self-oscillation tends to happen compared with the other versions, so please be careful about a lower limit of C_0 . A self-oscillation becomes easy to happen coldly, so please be careful and do initial evaluation.

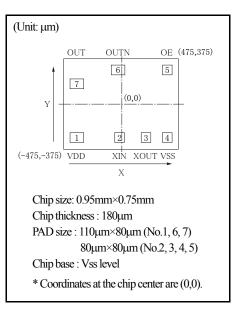
 R_1 in the F version is a fundamental wave (\leq 250MHz) 50 Ω in 3rd overtone (\leq 220MHz), and 20 Ω is an aim.

ORDERING INFORMATION

Device	Package	Version Name				
WF5060Hxx-3	Wafer form	Form WF:Wafer form CF:Chip (Die) form $WF5060H \square \square -3$ $\bigcirc Output frequency 6: f_0 7: f_0/2$ $\bigcirc Oscillation frequency$				
CF5060Hxx-3	Chip form	L : 25 to 100MHz, M : 100 to 175MHz A : 50 to 63MHz, B : 62 to 80MHz, C : 80 to 107MHz D : 100 to 140MHz, E : 140 to 175MHz F : 175 to 220MHz (3rd overtone) 175 to 250MHz (Fundamental)				

^{*2.} The oscillator circuit is optimized for 5032 to 3225 size crystal. In use of 7050 size crystal with large C₀ value, because the risk that oscillation margin is insufficient increases, it must be carefully evaluated.

PAD LAYOUT

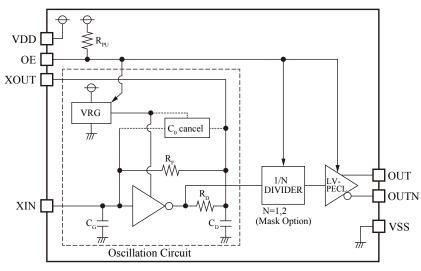


PIN DESCRIPTION and PAD COORDINATES

No.	Pin	I/O*1	Function	PAD coord	inates [µm]
INO.	ГШ	ľO	Function	X	Y
1	VDD	-	(+) supply voltage	-363.7	-283.5
2	XIN	Ι	Crystal connection pins	-11.7	-283.5
3	XOUT	0	Crystal is connected between XIN and XOUT.	208.2	-283.5
4	VSS	-	(-) ground	383.5	-283.5
5	OE	Ι	Input pin controlled output state (oscillator stops when Low), Power-saving pull-up resistor built-in	383.5	283.5
6	OUTN	0	LV-PECL output pin (Inverting output)	-29.1	283.5
7	OUT	0	LV-PECL output pin (Non-inverting output)	-368.5	168.2

*1. I: Input pin O: Output pin

BLOCK DIAGRAM



*. The C_{G} and C_{D} of the F version is only parasitic capacitance.

SPECIFICATIONS

Absolute Maximum Ratings

Vss=0V

Parameter	Symbol	Condition	Rating	Unit
Supply voltage range ^{*1}	V _{DD}	Between VDD and VSS	-0.3 to +4.0	V
Input voltage range ^{*1*2}	$V_{I\!N}$	Input pins	-0.3 to VDD+0.3	V
Output voltage range ^{*1*2}	V _{OUT}	Output pins	-0.3 to VDD+0.3	V
Junction temperature ^{*3}	Tj		+150	°C
Storage temperature range ^{*4}	T _{STG}	Chip form, Wafer form	-55 to~+150	°C

*1. This parameter rating is the values that must never exceed even for a moment. This product may suffer breakdown if this parameter rating is exceeded. Operation and characteristics are guaranteed only when the product is operated at recommended operating conditions.

*2. V_{DD} is a V_{DD} value of recommended operating conditions.

*3. Do not exceed the absolute maximum ratings. If they are exceeded, a characteristic and reliability will be degraded.

*4. When stored in nitrogen or vacuum atmosphere applied to IC itself only (excluding packaging materials).

Recommended Operating Conditions

Vss=0V

Parameter	Symbol	(MIN	ТҮР	MAX	Unit		
		5060HL7		25	-	100		
		5060HM6		100	-	175		
		5060HA6		50	-	63		
		5060HB6		62	-	80		
Oscillator frequency ^{*1}	f_0	5060HC6		80	-	107	MHz	
		5060HD6		100	-	140		
		5060HE6		140	-	175		
			3rd overtone	175	-	220		
		5060HF6	Fundamental	175	-	250	1	
		5060HL7		12.5	-	50		
		5060HM6		100	-	175		
		5060HA6		50	-	63		
		5060HB6		62	-	80		
Output frequency	f _{OUT}	5060HC6		80	-	107	MHz	
		5060HD6		100	-	140		
		5060HE6		140	-	175		
			3rd overtone	175	-	220		
		5060HF6	Fundamental	175	-	250		
Operating supply voltage	V _{DD}	Between VDD and VSS ^{*2}		2.25	-	3.63	V	
Input voltage	V _{IN}	Input pins		0	-	V _{DD}	V	
Operating temperature	Ta	~ *		-40	-	+125	°C	
Output load resistance	R _L	OUT pin, OUTN	pin, Terminated to V _{DD} -2V	49.5	-	50.5	Ω	

*1. The oscillation frequency is a yardstick value derived from the crystal used for NPC characteristics authentication. However, the oscillation frequency range is not guaranteed. Specifically, the characteristics can vary greatly due to crystal characteristics and mounting conditions, so the oscillation characteristics of components must be carefully evaluated.

*2. Mount a ceramic chip capacitor that is larger than 0.01µF proximal to IC (within approximately 3mm) between VDD and VSS in order to obtain stable operation of 5060H series. In addition, the wiring pattern between IC and capacitor should be as wide as possible.

Note. Since it may influence the reliability if it is used out of range of recommended operating conditions, this product should be used within this range.

Electrical Characteristics DC Characteristics

Measurement circuits 1 to 3 in "Conditions" are shown in "MEASUREMENT CIRCUITS."

Parameter	Symbol	C	onditions		MIN	ТҮР	MAX	Unit
	$I_{DDL}3.3V$		T <u>a</u> ≤+85°C	V _{DD} =3.3V	-	44.0	54.0	mA
Current consumption	I _{DDL} _2.5V	Measurement circuit 1 OE=Open	1 <u>a_</u> +05 C	V _{DD} =2.5V	-	41.0	51.0	112 1
(HL7 ver.)	I _{DDL} _3.3V	f ₀ =100MHz	T _a >+85°C	V _{DD} =3.3V	-	-	56.0	mA
	I _{DDL} _2.5V	•	1 _a +05 C	V _{DD} =2.5V	-	-	53.0	112 1
	I _{DDM} _3.3V		T _a ≤+85°C	V _{DD} =3.3V	-	46.0	55.0	mA
Current consumption	$I_{DDM}_{2.5V}$	Measurement circuit 1 OE=Open	1 <u>a</u> -105 C	V _{DD} =2.5V	-	42.0	50.0	IIIA
(HM6 ver.)	$I_{DDM}3.3V$	f ₀ =156.25MHz	T _a >+85°C	V _{DD} =3.3V	-	-	57.0	mA
	$I_{DDM}_{2.5V}$	10 100.20101112	1 _a +05 C	V _{DD} =2.5V	-	-	53.0	IIIA
	$I_{DDA}3.3V$		T <u>a</u> ≤+85°C	V _{DD} =3.3V	-	45.5	54.5	mA
Current consumption	I _{DDA} _2.5V	Measurement circuit 1	1 <u>a≥</u> ⊤85 C	V _{DD} =2.5V	-	42.5	51.0	mA
(HA6 ver.)	I _{DDA} _3.3V	OE=Open f ₀ =62.5MHz	T > 195%	V _{DD} =3.3V	-	-	56.5	mA
	I _{DDA} _2.5V	10 02.010112	T _a >+85°C	V _{DD} =2.5V	-	-	53.0	mA
	I _{DDB} _3.3V		T <1959C	V _{DD} =3.3V	-	46.0	55.0	
Current consumption	I _{DDB} _2.5V	Measurement circuit 1	T <u>a</u> ≤+85°C	V _{DD} =2.5V	-	43.0	51.5	mA
(HB6 ver.)	I _{DDB} _3.3V	OE=Open f ₀ =80MHz	T > 1959C	V _{DD} =3.3V	-	-	57.5	
	I _{DDB} _2.5V	10 0011112	T _a >+85°C	V _{DD} =2.5V	-	-	53.5	mA
	I _{DDC} _3.3V		T < 1959C	V _{DD} =3.3V	-	49.0	56.0	
Current consumption	I _{DDC} _2.5V	Measurement circuit 1	T <u>a</u> ≤+85°C	V _{DD} =2.5V	-	45.5	52.0	mA
(HC6 ver.)	I _{DDC} _3.3V	OE=Open f ₀ =106.25MHz	T > + 959C	V _{DD} =3.3V	-	-	58.0	
	I _{DDC} _2.5V	10 100.25101112	T _a >+85°C	V _{DD} =2.5V	-	-	54.0	mA
	I _{DDD} _3.3V		T < 1959C	V _{DD} =3.3V	-	49.0	56.0 m 52.0 m	
Current consumption	I _{DDD} _2.5V	Measurement circuit 1	T <u>a</u> ≤+85°C	V _{DD} =2.5V	-	45.5		mA
(HD6 ver.)	I _{DDD} _3.3V	OE=Open f ₀ =125MHz	T > + 959C	V _{DD} =3.3V	-	-	58.0	
	I _{DDD} _2.5V	10 12510112	T _a >+85°C	V _{DD} =2.5V	-	-	54.0	mA
	I _{DDE} _3.3V		T <1959C	V _{DD} =3.3V	-	50.0	57.0	
Current consumption	I _{DDE} _2.5V	Measurement circuit 1	T <u>a</u> ≤+85°C	V _{DD} =2.5V	-	46.0	52.5	mA
(HE6 ver.)	I _{DDE} _3.3V	OE=Open f ₀ =156.25MHz	$V_{\rm DD}=3$	V _{DD} =3.3V	-	-	59.0	
	I _{DDE} _2.5V	10 150.25101112	T _a >+85°C	V _{DD} =2.5V	-	-	54.5	mA
Current consumption	I _{DDF} _3.3V	Measurement circuit 1, 0	DE=Open	V _{DD} =3.3V	-	53.0	66.0	
(HF6 ver.)	I _{DDF} _2.5V	f ₀ =200MHz	Ĩ	V _{DD} =2.5V	-	48.0	61.0	mA
0. 1	Ţ	Measurement circuit 1		T <u>a</u> ≤+85°C	-	-	15	
Standby current	I _{STB}	OE=Low		T _a >+85°C	-	-	30	μA
	V _{OH}	Measurement circuit 2		T <u>a</u> ≤+85°C	V _{DD} -1.025	V _{DD}	V _{DD}	V
High-level output voltage	V OH		T_a>+85°C	V _{DD} -1.040	-0.950	-0.880	•	
Low-level output voltage	V _{OL}	Measurement circuit 2, 0	OUT/OUTN pir	1	V _{DD} -1.810	V _{DD} -1.700	V _{DD} -1.620	V
Output leakage current	IZ	Measurement circuit 3,	OE=Low, OUT	Γ/OUTN pin	-	-	10	μA
High-level input voltage	V _{IH}	Measurement circuit 1,	OE pin		$0.7V_{DD}$	-	-	V
Low-level input voltage	$V_{I\!L}$	Measurement circuit 1,	OE pin		-	-	$0.3V_{DD}$	V

Parameter	Symbol	Conditions	MIN	ТҮР	MAX	Unit
OE nin mull un registence	R _{PU1}	Measurement circuit 1	0.2	1	8	MΩ
OE pin pull-up resistance	R _{PU2}	Measurement circuit 1	30	70	150	kΩ
Oscillator feedback resistance (HL7 ver.)	R _{FL}	Design value	50	100	200	kΩ
Oscillator feedback resistance (HM6 ver.)	R _{FM}	Design value	50	100	200	kΩ
Oscillator feedback resistance (HA6 ver.)	R _{FA}	Design value	1.2	2.4	3.6	kΩ
Oscillator feedback resistance (HB6 ver.)	R _{FB}	Design value	1.1	2.2	3.3	kΩ
Oscillator feedback resistance (HC6 ver.)	R _{FC}	Design value	1.1	2.2	3.3	kΩ
Oscillator feedback resistance (HD6 ver.)	R _{FD}	Design value	1.1	2.2	3.3	kΩ
Oscillator feedback resistance (HE6 ver.)	R _{FE}	Design value	1.1	2.2	3.3	kΩ
Oscillator feedback resistance (HF6 ver.)	R _{FF}	Design value	0.95	1.9	2.85	kΩ
Oscillator capacitance	C _{GL}	Design value.	9.6	12.0	14.4	14.4 pF
(HL7 ver.)	C _{DL}	Excluding parasitic capacitance ^{*1}	11.2	14.0	16.8	pr
Oscillator capacitance	C _{GM}	Design value.	1.6	2.0	2.4	ъĘ
(HM6 ver.)	C _{DM}	Excluding parasitic capacitance ^{*1}	1.6	2.0	2.4	pF
Oscillator capacitance	C _{GA}	Design value.	8.0	10.0	12.0	щE
(HA6 ver.)	C _{DA}	Excluding parasitic capacitance ^{*1}	11.2	14.0	16.8	pF
Oscillator capacitance	C _{GB}	Design value.	8.0	10.0	12.0	щĘ
(HB6 ver.)	C _{DB}	Excluding parasitic capacitance ^{*1}	9.6	12.0	14.4	pF
Oscillator capacitance	C _{GC}	Design value.	3.2	4.0	4.8	щĘ
(HC6 ver.)	C _{DC}	Excluding parasitic capacitance ^{*1}	3.2	4.0	4.8	pF
Oscillator capacitance	C _{GD}	Design value.	1.6	2.0	2.4	F
(HD6 ver.) C _{DD}		Excluding parasitic capacitance ^{*1}	1.6	2.0	2.4	pF
Oscillator capacitance	C _{GE}	Design value.	0.8	1.0	1.2	
(HE6 ver.)	C _{DE}	Excluding parasitic capacitance ^{*1}	0.8	1.0	1.2	pF
Oscillator capacitance	C _{GF}	Design value.	-	0	-	F
(HF6 ver.)	C _{DF}	Excluding parasitic capacitance ^{*1}	-	0	-	pF

*1. Confirmed by sampling inspection of the monitor pattern on the wafer.

AC Characteristics

Measurement circuits 4 and 5 in "Conditions" are shown in "MEASUREMENT CIRCUITS."

The conditions for each parameter assume the timing shown in "Timing Diagram."

 $V_{DD} = 2.25$ to 3.63V, $V_{SS} = 0V$, $T_a = -40$ to $+125^{\circ}C$ unless otherwise noted

Parameter	Symbol		Conditions					MAX	Unit		
Output duty cycle 1 (Differential output)	Duty1		Measurement circuit 4 Measured at differential output signal 0V (crossing point)			45	-	55	%		
Output duty cycle 2 (Single-ended output)	Duty2	Measurement circ Measured at 50%		ed output swing	Ş	45	-	55	%		
Output swing	V _{OPP}	Measurement circ	uit 4, singl	e-ended output s	signal	0.4	-	-	V		
			HA6		$2.97V \leq V_{DD} \leq 3.63V$	-	200	400			
			HB6 HC6	$T_a \leq +85^{\circ}C$	$2.375V \le V_{DD} \le 2.97V$	-	250	500			
		Measurement	HD6 HE6		$2.25V \le V_{DD} \le 2.375V$	-	300	600			
Q 4 4 5 7 *1		circuit 4, Measured at	HL7 HM6	T > 10500	$2.97V \leq V_{DD} \leq 3.63V$	-	-	500			
Output rise time ^{*1} t _r	20% to 80%	ver.	T _a >+85°C	$2.25V \le V_{DD} \le 2.97V$	-	-	600	ps			
	single-ended output swing	2		$2.97V \leq V_{DD} \leq 3.63V$	-	200	400				
		oupursting			HF6 ver	:	$2.375V \le V_{DD} \le 2.97V$	-	250	500	
			$2.25V \le V_{DD} \le 2.375V$		-	300	600				
			HA6		$2.97V \leq V_{DD} \leq 3.63V$	-	200	400			
			HB6 HC6 HD6 HE6	HB6 HC6	_	T _a ≤+85°C	$2.375V \le V_{DD} < 2.97V$	-	250	500	
		Measurement			$2.25V \le V_{DD} \le 2.375V$	-	300	600			
o		circuit 4, Measured at	HL7		$2.97V \le V_{DD} \le 3.63V$	-	-	500			
Output fall time ^{*2}	t _f	80% to 20%	HM6 ver.	T _a >+85°C	$2.25V \le V_{DD} \le 2.97V$	-	-	600	ps		
		single-ended output swing		1	$2.97V \leq V_{DD} \leq 3.63V$	-	200	400			
	oupursting	HF6 ver		$2.375V \le V_{DD} \le 2.97V$	-	250	500				
		$2.25V \le V_{DD} \le 2.375V$		-	300	600					
Output disable time	t _{OD}	Time until Hi-Z is	Measurement circuit 5 Time until Hi-Z is output at OE(fall)= V_{IL} (Refer to the timing chart for details.)			-	-	200	ns		

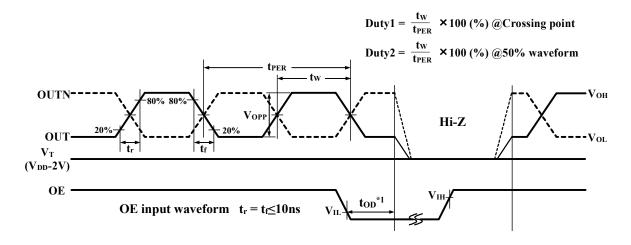
*1. Measurement circuit 4, Measured between 20% and 80% amplitude of single-ended signal

*2. Measurement circuit 4, Measured between 80% and 20% amplitude of single-ended signal

* The ratings above are values obtained by measurements using an NPC evaluation standard crystal element, standard testing jig, and evaluation package. Ratings may have wide tolerances due to crystal element characteristics, evaluation jig, and package parasitic capacitance, so thorough evaluation is recommended.

Timing Diagram

The timing diagram applies to the "Conditions" in the table in "AC Characteristics."



*1. The OUT/OUTN output goes high impedance after the OE is fallen and then the output disable time " t_{OD} " has elapsed. The output signal is pulled down to V_T (terminated voltage) by load resistance.

FUNCTIONAL DESCRIPTION

OE Function

When OE goes LOW, the OUT/OUTN outputs stop and become high impedance. This function is used to disable the operation of the device.

OE	OUT/OUTN	Oscillator
High or Open	$f_0, f_0/2$	Operating
Low	Hi-Z	Stopped

Power Saving Pull-up Resistor

The OE terminal pull-up resistance switches between R_{PU1} and R_{PU2}, depending on the input level (HIGH or LOW).

When the OE terminal is held LOW, the built-in OE terminal pull-up resistance increases (R_{PU1}), reducing the current consumed by the pull-up resistance when the outputs are disabled.

When the device is operating with the OE terminal HIGH or open circuit, the pull-up resistance decreases (R_{PU2}), reducing internal susceptibility to the effects of external noise. The OE terminal is held HIGH internally to prevent problems that might otherwise cause the outputs to stop abruptly.

Oscillation Detection Function

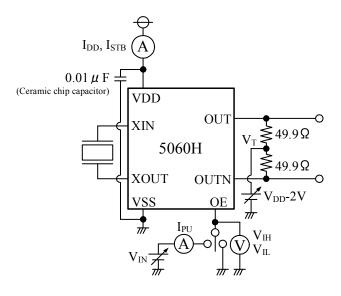
The IC has a built-in oscillation detection circuit. The oscillation detection circuit disables the output circuit when the oscillator starts until the oscillation becomes stable. This function limits the danger of unstable oscillation when the oscillator starts after power is first applied or the output is enabled.

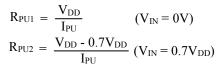
C₀ cancellation circuit

Oscillation circuit with a built-in C_0 cancellation circuit provides a fixed compensation amount to cancel the effect of the crystal C_0 . It reduces the C_0 parameter in the equivalent circuit, reducing the shallow negative resistance for increasing values of C_0 . This cancellation circuit makes it easier to maintain the oscillation margin.

MEASUREMENT CIRCUITS MEASUREMENT CIRCUIT 1

Measurement Parameter : I_{DD} , I_{STB} , V_{IH} , V_{IL} , R_{PU1} , R_{PU2}

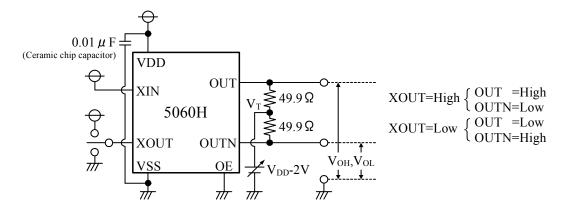




 $\begin{array}{l} V_{IH}: V_{SS} {\rightarrow} V_{DD} \text{ voltage that changes output state} \\ V_{IL}: V_{DD} {\rightarrow} V_{SS} \text{ voltage that changes output state} \end{array}$

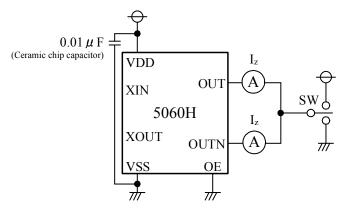
MEASUREMENT CIRCUIT 2

Measurement Parameter : V_{OH} , V_{OL}



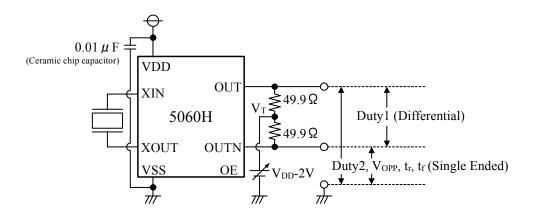
MEASUREMENT CIRCUIT 3

Measurement Parameter : Iz



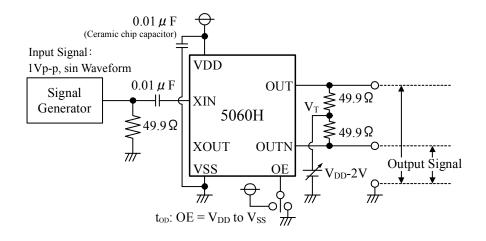
MEASUREMENT CIRCUIT 4

Measurement Parameter : Duty1, Duty2, V_{OPP} , t_r , t_f



MEASUREMENT CIRCUIT 5

Measurement Parameter : t_{OD}



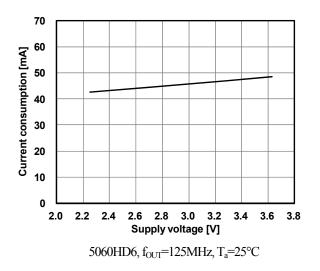
REFERENCE DATA

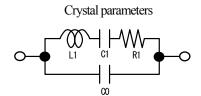
The following characteristics are measured using the crystal below. Note that the characteristics will vary with the crystal used.

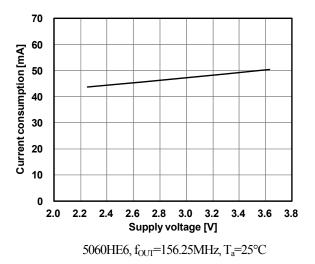
Crystal used for measurement ((3rd overtone)
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Parameter	f ₀ =125.00MHz	f ₀ =156.25MHz
C ₀ (pF)	1.8	1.2
$R_1(\Omega)$	35	60

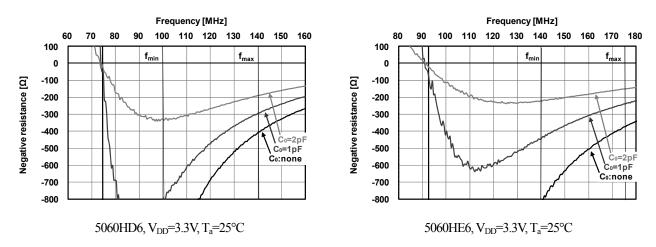




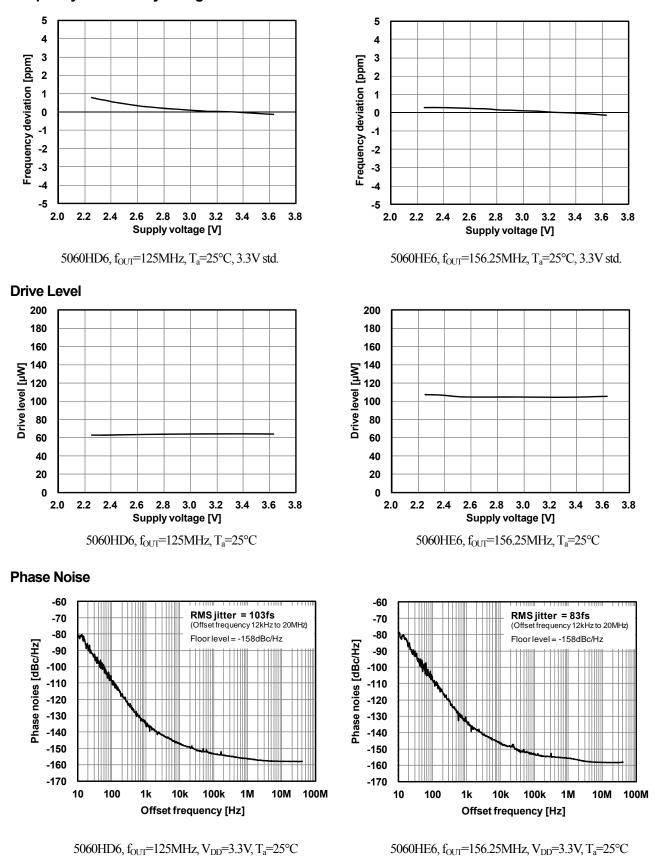




Negative Resistance



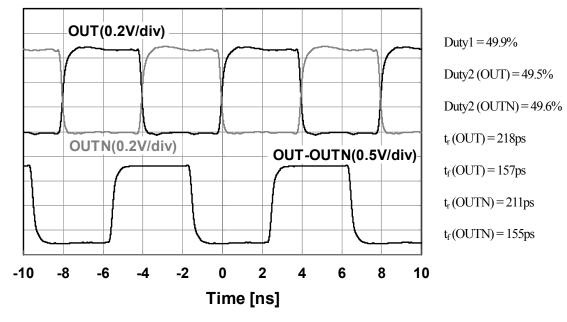
The figures show the measurement result of the crystal equivalent circuit C_0 capacitance, connected between the XIN and XOUT pins. They were performed with Agilent 4396B using the NPC test jig. They may vary in a measurement jig, and measurement environment.



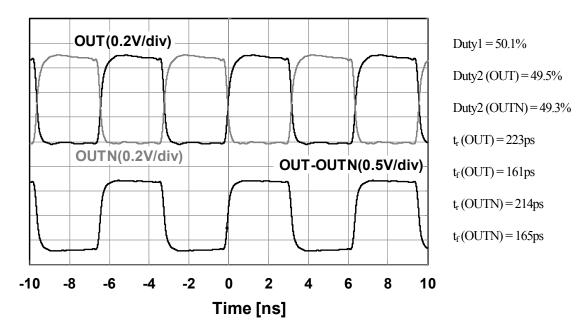
Frequency Deviation by Voltage



Output Waveform



5060HD6, f_{OUT} =125MHz, V_{DD} =3.3V, T_a =25°C



5060HE6, f_{OUT}=156.25MHz, V_{DD}=3.3V, T_a=25°C

Measurement equipment: Oscilloscope DSO80604B (Agilent) Differential probe 1134A (Agilent) Probe head E2675A (Agilent)

APPLICATION CIRCUIT (TERMINATION CIRCUIT)

This section describes sample termination circuits that can be used with the device. The termination circuits use chip resistors, and care should be taken to prevent resistance value mismatch. Also, the length of wiring between the outputs and termination resistance should be as short as possible to prevent mismatch. Chip capacitors are used for the bypass capacitors and should be placed as close as possible to the device terminals.

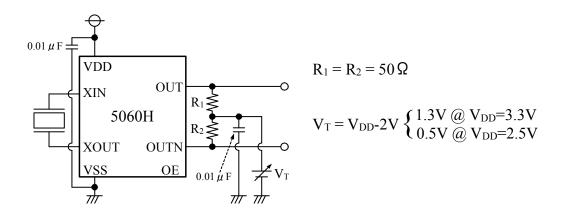
These application circuit examples are provided as reference circuit diagrams only, and do not represent circuits guaranteed by NPC. We accept no responsibility from any damage or less resulting from their use. Always use devices after conducting thorough evaluation.

TERMINATION CIRCUIT1 (RECOMMENDED CIRCUIT)

This is a standard LV-PECL termination circuit identical to the circuit in measurement circuit 4.

The characteristics values in "Electrical Characteristics" are based on the measurement results obtained using this circuit. It uses an external V_{DD} -2V supply and provides a 50 Ω termination.

Problems due to differences in the output characteristics are minimized, allowing characteristics close to ideal to be obtained. Additional wiring pattern to apply the termination voltage V_T must be prepared on the evaluation board.



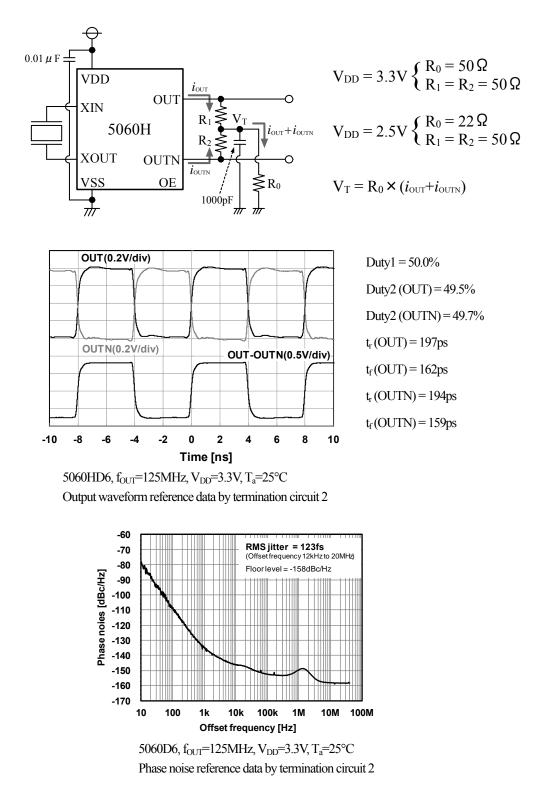
TERMINATION CIRCUIT2

This method creates the V_{DD}-2V termination voltage using a voltage drop $R_0 \times (i_{OUT} + i_{OUTN})$ obtained by connecting a resistor between V_T and V_{SS}. As there is no requirement to supply the termination voltage V_T from an external supply, the circuit can operate from a single power supply. However, the termination voltage V_T wiring pattern must be prepared on the evaluation board.

Differences in the output characteristics may occur due to differences in the values of R_0 and V_{DD} .

Operation at V_{DD}=3.3V and 2.5V requires different values of resistance for R₀.

It is possible to obtain improved characteristics by connecting a 1000 pF capacitor directly to the termination resistance $R_1(R_2)$ - V_T junction.



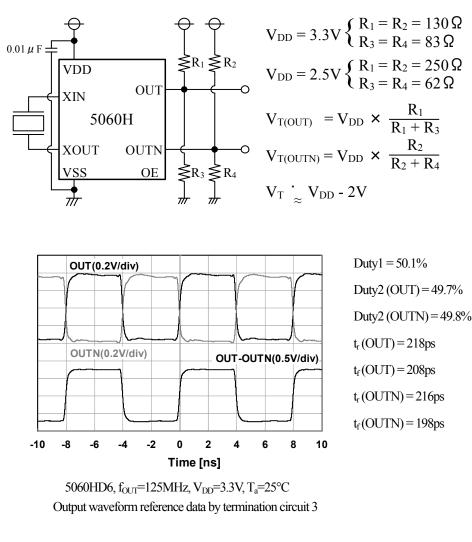
TERMINATION CIRCUIT3

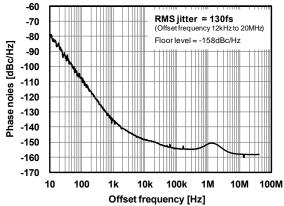
This circuit employs a voltage divider using pairs of resistors to obtain a parallel resistance of 50Ω .

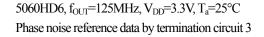
As there is no requirement to supply the termination voltage V_T from an external supply, the circuit can operate from a single power supply. Also, termination voltage V_T pattern wiring is not required.

Differences in the output characteristics may occur due to differences in the values of R1 to R4 and VDD.

Operation at V_{DD}=3.3V and 2.5V requires different values of resistance for R₁ to R₄.



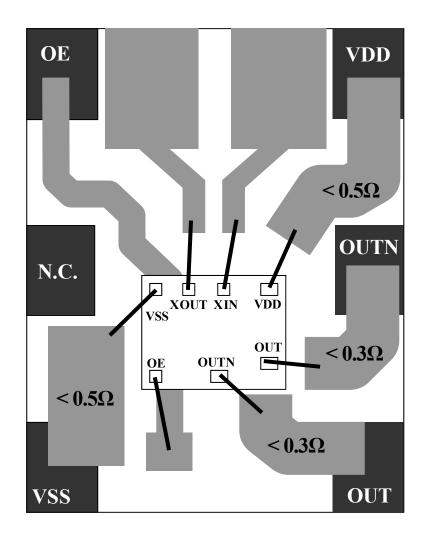




MOUNTING PRECAUTIONS

This device is an oscillator IC designed for use in miniature crystal oscillators, and is susceptible to parasitic components caused by device mounting conditions. Observe the following points in order to obtain the best characteristics.

- The VDD and VSS wiring resistance (pattern resistance) should be less than 0.5Ω.
- The OUT and OUTN wiring resistance (pattern resistance) should be less than 0.3Ω .
- The OUT and OUTN pattern wiring including the bonding, should be of equal length in order to obtain best device characteristics.



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